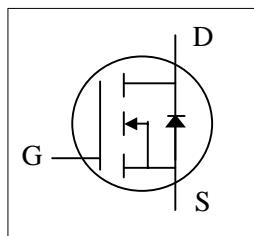
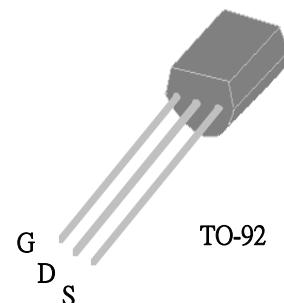




- ▼ 100% Avalanche Test
- ▼ Fast Switching Characteristics
- ▼ Simple Drive Requirement



$BV_{DSS}$	600V
$R_{DS(ON)}$	5Ω
$I_D$	400mA



## Description

Advanced Power MOSFETs utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

The TO-92 package is widely used for commercial-industrial applications.

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	600	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D @ T_L = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	400	mA
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	3	A
$P_D @ T_L = 25^\circ C$	Total Power Dissipation	2	W
	Linear Derating Factor	0.017	W/°C
$E_{AS}$	Single Pulse Avalanche Energy <sup>2</sup>	20	mJ
$I_{AR}$	Avalanche Current	2	A
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	150	°C/W
$R_{thj-l}$	Maximum Thermal Resistance, Junction-lead	60	°C/W

**Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=1\text{mA}$	600	-	-	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=400\text{mA}$	-	-	5	$\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\text{\mu A}$	2	-	4	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=400\text{mA}$	-	570	-	$\text{mS}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$	-	-	100	$\text{\mu A}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=\pm 30\text{V}$	-	-	$\pm 1$	$\text{\mu A}$
$Q_g$	Total Gate Charge <sup>3</sup>	$I_{\text{D}}=2\text{A}$	-	12	19	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=480\text{V}$	-	2	-	$\text{nC}$
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=10\text{V}$	-	5.5	-	$\text{nC}$
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>3</sup>	$V_{\text{DD}}=200\text{V}$	-	10	-	ns
$t_r$	Rise Time	$I_{\text{D}}=1\text{A}$	-	12	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_G=50\Omega, V_{\text{GS}}=10\text{V}$	-	52	-	ns
$t_f$	Fall Time	$R_D=200\Omega$	-	19	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	375	600	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=10\text{V}$	-	170	-	$\text{pF}$
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	45	-	$\text{pF}$

**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>3</sup>	$T_j=25^\circ\text{C}, I_s=2\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.5	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>3</sup>	$I_s=2\text{A}, V_{\text{GS}}=0\text{V},$	-	340	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI/dt=100\text{A}/\mu\text{s}$	-	2.2	-	$\text{\mu C}$

**Notes:**

- 1.Pulse width limited by Max. junction temperature.
- 2.Starting  $T_j=25^\circ\text{C}$  ,  $V_{\text{DD}}=50\text{V}$  ,  $L=10\text{mH}$  ,  $R_G=25\Omega$
- 3.Pulse test

THIS PRODUCT IS AN ELECTROSTATIC SENSITIVE, PLEASE HANDLE WITH CAUTION.

THIS PRODUCT HAS BEEN QUALIFIED FOR CONSUMER MARKET. APPLICATIONS OR USES AS CRITERIAL COMPONENT IN LIFE SUPPORT DEVICE OR SYSTEM ARE NOT AUTHORIZED.

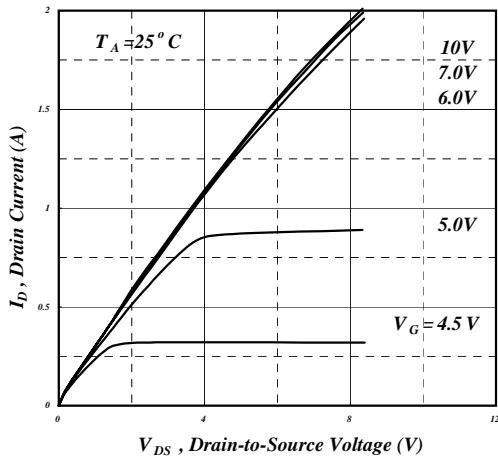


Fig 1. Typical Output Characteristics

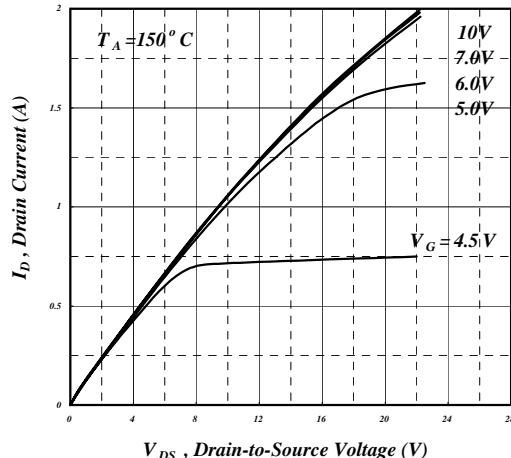


Fig 2. Typical Output Characteristics

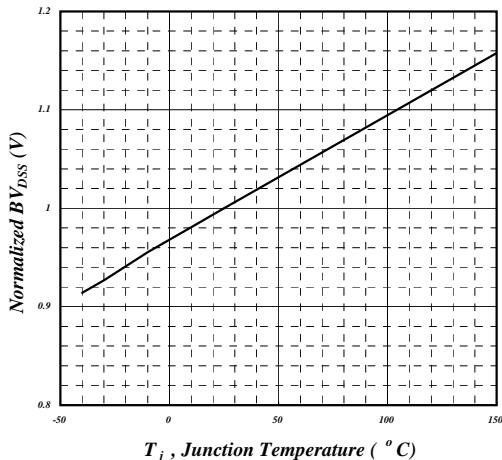
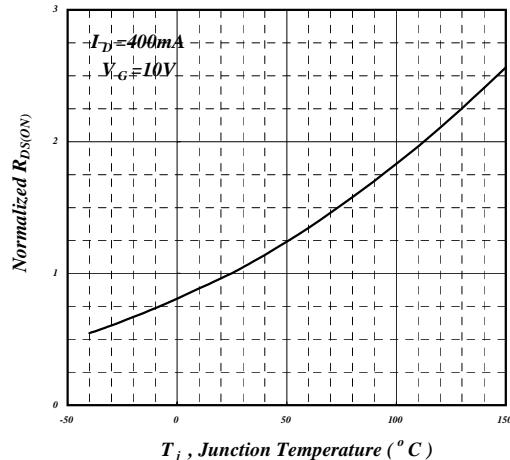
Fig 3. Normalized  $BV_{DSS}$  v.s. Junction Temperature

Fig 4. Normalized On-Resistance v.s. Junction Temperature

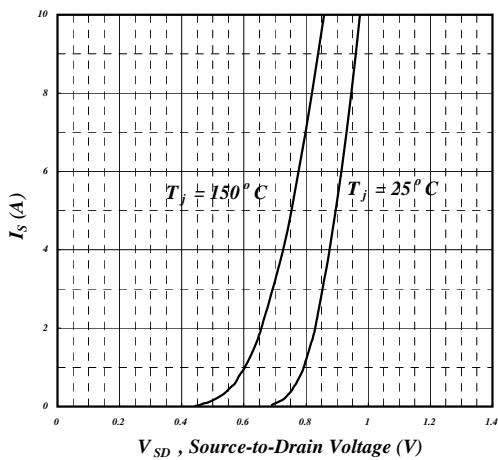


Fig 5. Forward Characteristic of Reverse Diode

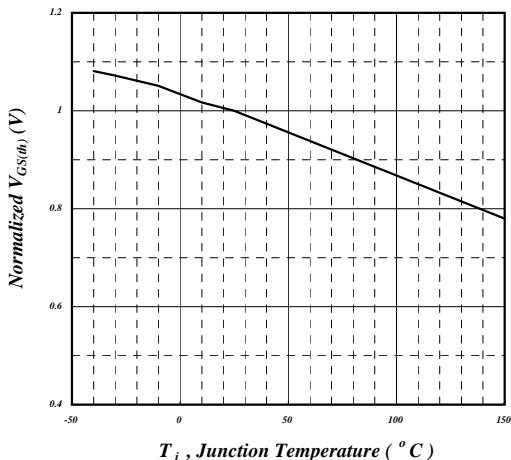
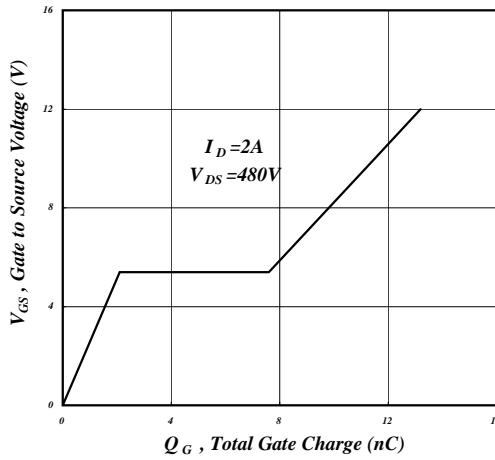
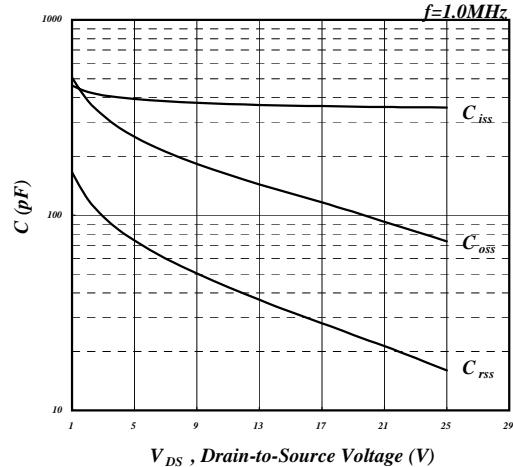


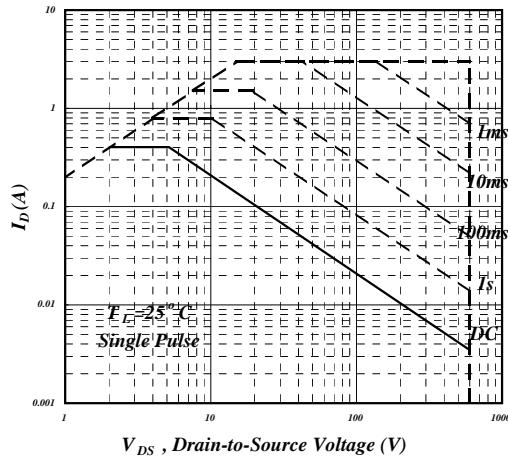
Fig 6. Gate Threshold Voltage v.s. Junction Temperature



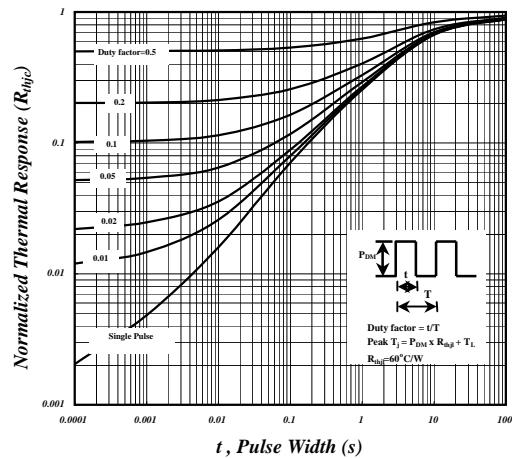
**Fig 7. Gate Charge Characteristics**



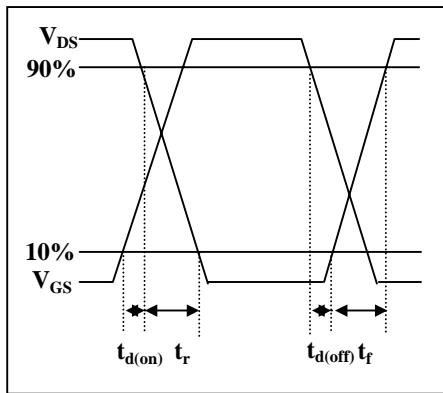
**Fig 8. Typical Capacitance Characteristics**



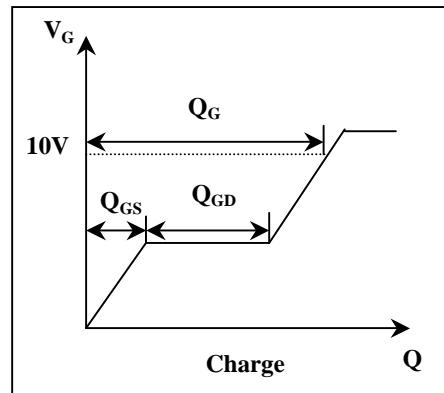
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Switching Time Waveform**

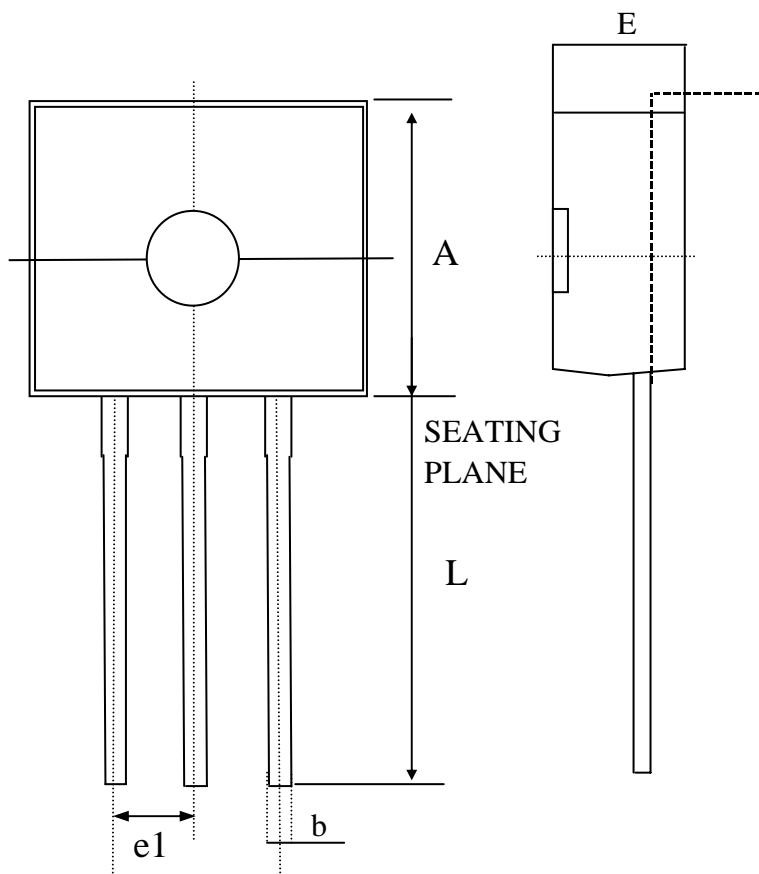


**Fig 12. Gate Charge Waveform**



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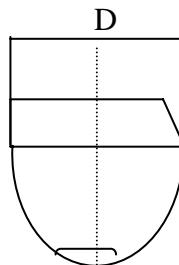
## Package Outline : TO-92



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	4.32	4.83	5.34
D	4.1	4.8	5.3
E	3.1	3.9	4.7
b	----	0.38	----
L	12.7	---	----
e1	----	1.27	----

1. All Dimensions Are in Millimeters.

2. Dimension Does Not Include Mold Protrusions.



## Part Marking Information & Packing : TO-92

